



PK822(v1.0) November 30, 2016

100% Material Declaration Data Sheet for 7-Series (Artix) FBG484 RoHS 6/6

Average Weight : 2.1467 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00	basis	0.237468	11.062%
					0.237468	
Bump					0.011258	0.524%
	Sn	7440-31-5	98.20	basis	0.011055	
	Ag	7440-22-4	1.80	basis	0.000203	
					0.034000	1.584%
Underfill	Bisphenol F type liquid epoxy	9003-36-5	15.00	basis	0.005100	
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.003400	
	Bisphenol A type liquid epoxy	25068-38-6	5.00	basis	0.001700	
	Amine type hardener	trade secret	10.00	basis	0.003400	
	Silicon dioxide	60676-86-0	58.00	filler	0.019720	
	Carbon black	1333-86-4	1.00	color agent	0.000340	
	Additives	trade secret	1.00	additives	0.000340	
					0.404317	18.834%
Solder ball	Sn	7440-31-5	96.50	Main material	0.390166	
	Ag	7440-22-4	3.00	Main material	0.012130	
	Cu	7440-50-8	0.50	Main material	0.002022	
					1.459657	67.995%
Substrate	Copper	7440-50-8	37.80		0.551750	
	Tin	7440-31-5	1.14		0.016640	
	Silver	7440-22-4	0.04		0.000584	
	Core	N/A	47.76		0.697132	
	ABF	N/A	10.87		0.158665	
	Solder Mask	N/A	2.39		0.034886	

Revision History

Date	Version	Description of Revisions
11/30/2016	1.0	Initial Xilinx release.